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## PRODUCTS IN THE NEWS

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#### Press Release Summary:

**December 21, 2015** - Samtec, Inc. will participate in the DesignCon 2016 conference and exhibition, January 19 - 21 at the Santa Clara Convention Center. Samtec will be featuring Silicon-to-Silicon product demonstrations, three 40-minute technical paper sessions, one 75-minute panel discussion and one 3-hour tutorial. The Silicon-to-Silicon product demonstration will include built-in pattern generation for bit rate, BER and eye pattern monitoring of each channel featuring FQSFP Series Flyover QSFP System, Z-Ray® One Piece Interposer, ExaMAX® High-Speed Backplane and SEARAY Open Pin Field Array interconnects.

The paper sessions will cover the following: successful design of high-speed interconnects in packages and backplanes through deep channel analysis, how a 28 Gbps backplane design can be optimized for cost utilizing different materials and advanced routing techniques, and a method to reliably test microwave interconnects for 12G-SDI applications. The panel discussion will cover the differences, challenges and limitations for both copper and optics in high performance applications, as well as the existing and upcoming industry capabilities and costs. The tutorial will teach a systematic approach to modeling dielectrics and conductors for interconnect design at 10-50 Gbps data rates.

Samtec, Inc. is an international supplier of interconnects, cable assemblies and design solutions. We focus on system optimization by combining innovative product solutions and signal integrity expertise. Our products include high-speed board level interconnects, high-speed cable assemblies, flyover and optical systems, IC packaging and procurement services, the industry's largest variety of board-to-board interconnects, and rugged and power systems. Samtec provides full channel system support, streamlining and optimizing the signal path, from the IC to the board and beyond.

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ExaMAX® high-speed backplane system delivers 28 Gbps electrical performance on a 2.00 mm column pitch while offering an easy migration path to 56 Gbps on a 3.00 mm column pitch. This gives designers the option of optimizing density or minimizing board layer count for high speed backplane applications. ExaMAX® connectors meet the Telcordia GR-1217 CORE specification and exceed OIF CEI-28G-LR specification for 28 Gbps standards. The beam-on-beam design provides two reliable points of contact, minimizes the residual stub for improved SI performance, and provides low mating force while maintaining excellent normal force. Signal wafers incorporate a one-piece, embossed ground structure, which improves crosstalk performance.

Samtec's Z-Ray® one piece arrays are ultra-low profile, high-density and highly customizable. These compression contact arrays are used as interposers or integrated into connector housings. Compared to standard interposers, they feature greater density, X-Y flexibility, height flexibility, increased cycle life, low normal force with high deflection range and up to 56 Gbps performance with a migration path to 100 Gbps. Z-Ray® is available on multiple pitches starting at 0.80 mm and profiles from 0.30 mm to 4.00 mm. Choice of fastener, alignment and screw options are available.

The new FQSFP Series is a flyover QSFP assembly that improves signal integrity by flying critical data over lossy PCB materials, thus providing more flexibility in the system architecture. The FQSFP achieves 28 Gbps performance and is backward compatible with all QSFP cable assemblies. No re-timers are required resulting in reduced costs and power consumption. Press-fit tails provide low speed signals and power to the PCB. Thermal dissipation is improved through power reduction and by freeing designers to place ICs in preferred locations. Full product release is expected Q1 2016.

**About DesignCon**

DesignCon, produced by UBM Canon, is the world's premier conference for chip, board and systems design engineers in the high-speed communications and semiconductor communities. DesignCon, created by engineers for engineers, takes place annually in Silicon Valley and remains the largest gathering of chip, board and systems designers in the country. This four-day technical conference and expo combines technical paper sessions, tutorials, industry panels, product demos and exhibits from the industry's leading experts and solutions providers. More information is available at: [www.designcon.com/santaclara/](http://www.designcon.com/santaclara/) (<http://www.designcon.com/santaclara/>).

Visit Samtec at Booth 619 or [www.samtec.com/designcon](http://www.samtec.com/designcon) (<http://www.samtec.com/designcon>) for more information on Samtec's full channel system capabilities and support.

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